

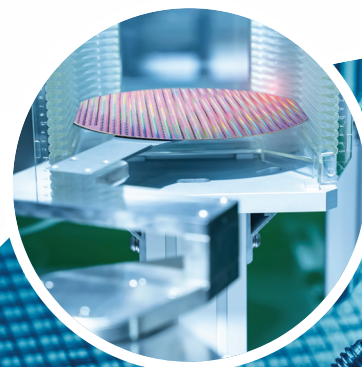
# EQUIPMENT DIVISION

Providing fabrication, assembly and test equipment for research and production of semiconductor devices and related technologies.

**Products & services include: wet benches for electro-plating, etching, cleaning, porous silicon formation and customised applications, lithography equipment for exposure, resist coating, development and cleaning, semiconductor oxidation and annealing furnaces, wafer bumping and probing systems, inspection systems & microscopes, temporary or permanent wafer bonders, dicing saws and diamond scribing machines, die bonders and sorters, sinter attach equipment, ultrasonic wire bonding machines, plasma cleaners and etching systems, vacuum solder reflow ovens and material testers for wire pull & bond-die shear testing etc.**

Supplying the UK, Ireland and Northern European regions, Inseto aims to exceed customer expectations and is committed to a policy of continuous improvement throughout the company.

Inseto's other product divisions comprise semiconductor Wafers for device fabrication, Materials for microelectronic assembly, plus Adhesives for electronic, automotive and industrial applications.



# ***inseto***

**ADVANCED TECHNOLOGY FOR RESEARCH & INDUSTRY**

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# EQUIPMENT DIVISION

## WET PROCESS EQUIPMENT



## INSPECTION SYSTEMS & MICROSCOPES



## INK JET PRINTING



## WAFER COATING & DEVELOPING



## MASK ALIGNERS



## IMPRINT LITHOGRAPHY



## PHOTOMASK CLEANING



## WAFER FURNACES



## WAFER BONDRERS



## SOLDER BUMPING



## PLASMA CLEAN & ETCH



## WAFER PROBERS



## DICING & SCRIBING



## DIE BONDRERS: MANUAL



## DIE BONDRERS: AUTOMATIC



## VACUUM REFLOW OVENS



## SINTER DIE ATTACH



## WIRE BONDRERS: MANUAL



## WIRE BOND: AUTOMATIC



## BOND & MATERIAL TEST

